

Title (en)

METHOD AND DEVICE FOR CLEANING A PRINTED-CIRCUIT BOARD MASK OR A PRINTED-CIRCUIT BOARD

Title (de)

VERFAHREN UND VORRICHTUNG ZUM REINIGEN EINER GEDRUCKTEN SCHALTUNG ODER EINER MASKE EINER GEDRUCKTEN SCHALTUNG

Title (fr)

PROCEDE ET DISPOSITIF POUR NETTOYER UN MASQUE DE CIRCUIT IMPRIME OU UN CIRCUIT IMPRIME

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Application

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Abstract (en)

[origin: DE19828987A1] A method and device are proposed for removing agents, in particular fluxes, adhesives or solder paste, which are adhering to a surface of a printed-circuit board mask or to a surface of a printed-circuit board in which the components may or may not have been inserted. The agents are removed by blasting at least one area of the surface of the printed-circuit board mask or of the printed-circuit board with at least one cleaning jet which contains carbon dioxide particles. The carbon dioxide particles are produced by shaving from a solid carbon dioxide body.

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